MINIATURIZED SEMICONDUCTOR PACKAGE ARRANGEMENT

ABSTRACT

There is disclosed a light weight and miniaturized electronic package or module (10), wherein the dimensions between an integrated circuit comprising a semiconductor chip (14) and those of a chip carrier (12) have been optimized in order to provide for minimum weight and size relationships. Furthermore, disclosed is a method of forming the semiconductor package arrangement to produce a small, lightweight and miniaturized chip-sized chip carrier package module. The chip carrier, which may be an organic laminate, multi-layer ceramic substrate or flexible substrate, as required by specific applications, is basically designed to possess overall smaller peripheral dimensions than those of the integrated circuit or simiconductor chip which is adapted to be mounted thereon. The chip carrier or substrate is electrically connected to the semiconductor chip through the intermediary of either solder bumps (30) or a conductive adhesive (20), or other suitable flip chip connection methods.

Fig 1